

SILICON N-CHANNEL DUAL GATE MOS-FET

Depletion type field-effect transistor in a plastic X-package with source and substrate interconnected. Intended for UHF applications, such as UHF television tuners, with 12 V supply voltage and professional communication equipment.

This MOS-FET tetrode is protected against excessive input voltage surges by integrated back-to-back diodes between gates and source.

QUICK REFERENCE DATA

Drain-source voltage	V_{DS}	max.	18 V
Drain current (DC)	I_D	max.	30 mA
Total power dissipation up to $T_{amb} = 75\text{ }^\circ\text{C}$	P_{tot}	max.	225 mW
Junction temperature	T_j	max.	150 $^\circ\text{C}$
Transfer admittance at $f = 1\text{ kHz}$ $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$	$ y_{fs} $	typ.	19 mS
Input capacitance at gate 1; $f = 1\text{ MHz}$	C_{ig1-s}	typ. max.	2.6 pF 3.0 pF
Feedback capacitance at $f = 1\text{ MHz}$ $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$	C_{rs}	typ.	25 fF
Noise figure at $G_S = 5\text{ mS}; B_S = B_S\text{ opt}$ $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}; f = 800\text{ MHz}$	F	typ.	2.0 dB

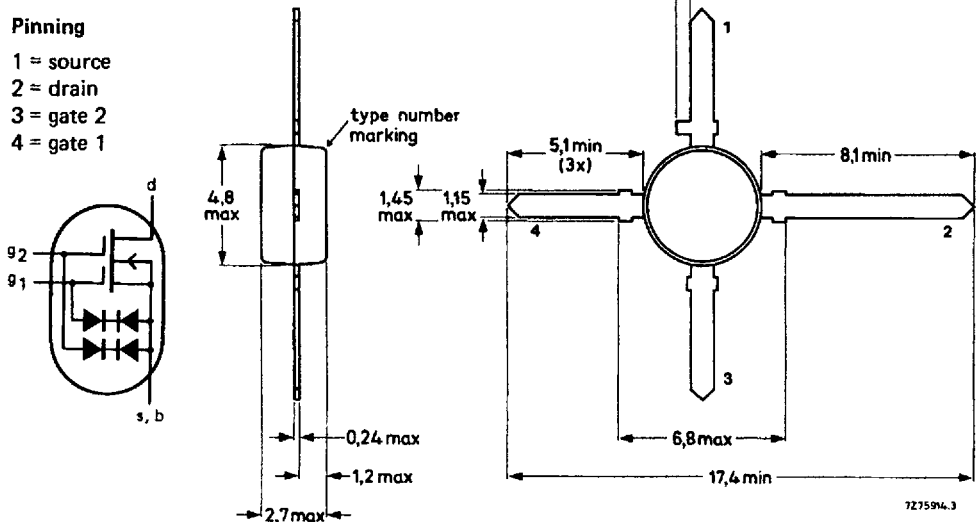
MECHANICAL DATA

Dimensions in mm

Fig.1 SOT103.

Pinning

- 1 = source
- 2 = drain
- 3 = gate 2
- 4 = gate 1



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Drain-source voltage	V_{DS}	max.	18 V
Drain current (DC or average)	I_D	max.	30 mA
Gate 1 - source current	$\pm I_{G1-S}$	max.	10 mA
Gate 2 - source current	$\pm I_{G2-S}$	max.	10 mA
Total power dissipation up to $T_{amb} = 75\text{ }^\circ\text{C}$	P_{tot}	max.	225 mW
Storage temperature range	T_{stg}		$-65\text{ to }+150\text{ }^\circ\text{C}$
Junction temperature	T_j	max.	150 $^\circ\text{C}$

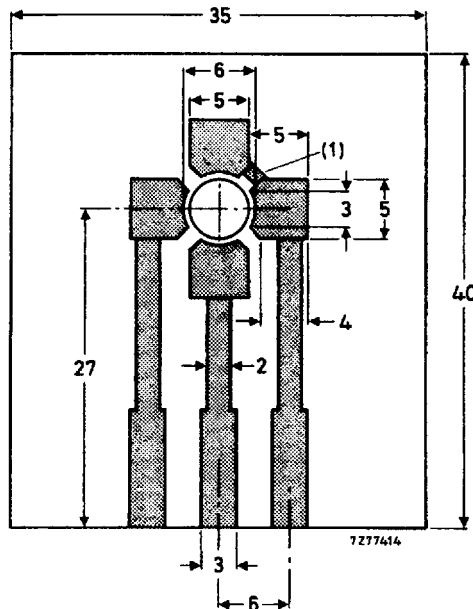
THERMAL RESISTANCE

From junction to ambient in free air

mounted on the printed-circuit board (see Fig.2)

$$R_{thj-a} = 335\text{ K/W}$$

Dimensions in mm



(1) Connection made by a strip or Cu wire.

Fig.2 Single-sided 35 μm Cu-clad epoxy fibre-glass printed-circuit board, thickness 1.5 mm. Tracks are fully tin-lead plated. Board in horizontal position for R_{th} measurement.

STATIC CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Gate cut-off currents

$$\pm V_{G1-S} = 7\text{ V}; V_{G2-S} = V_{DS} = 0$$

$$\pm I_{G1-SS} \quad \text{max.} \quad 25\text{ nA}$$

$$\pm V_{G2-S} = 7\text{ V}; V_{G1-S} = V_{DS} = 0$$

$$\pm I_{G2-SS} \quad \text{max.} \quad 25\text{ nA}$$

Gate-source breakdown voltages

$$\pm I_{G1-SS} = 10\text{ mA}; V_{G2-S} = V_{DS} = 0$$

$$\pm V_{(BR)G1-SS} \quad 8\text{ to }20\text{ V}$$

$$\pm I_{G2-SS} = 10\text{ mA}; V_{G1-S} = V_{DS} = 0$$

$$\pm V_{(BR)G2-SS} \quad 8\text{ to }20\text{ V}$$

Gate-source cut-off voltages

$$I_D = 20\text{ }\mu\text{A}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}$$

$$-V_{(P)G1-S} \quad \text{min.} \quad 0.2\text{ V}$$

$$\text{max.} \quad 1.3\text{ V}$$

$$I_D = 20\text{ }\mu\text{A}; V_{DS} = 10\text{ V}; V_{G1-S} = 0$$

$$-V_{(P)G2-S} \quad \text{min.} \quad 0.2\text{ V}$$

$$\text{max.} \quad 1.1\text{ V}$$

DYNAMIC CHARACTERISTICS

Measuring conditions (common source): $I_D = 10\text{ mA}; V_{DS} = 10\text{ V}; +V_{G2-S} = 4\text{ V}; T_{\text{amb}} = 25\text{ }^\circ\text{C}$

Transfer admittance at $f = 1\text{ kHz}$

$$|y_{fs}| \quad \text{min.} \quad 18\text{ mS}$$

$$\text{typ.} \quad 19\text{ mS}$$

Input capacitance at gate 1; $f = 1\text{ MHz}$

$$C_{ig1-s} \quad \text{typ.} \quad 2.6\text{ pF}$$

$$\text{max.} \quad 3.0\text{ pF}$$

Feedback capacitance at $f = 1\text{ MHz}$

$$C_{rs} \quad \text{typ.} \quad 25\text{ fF}$$

$$\text{max.} \quad 35\text{ fF}$$

Output capacitance at $f = 1\text{ MHz}$

$$C_{os} \quad \text{typ.} \quad 1.1\text{ pF}$$

Noise figure at $f = 800\text{ MHz}; G_S = 5\text{ mS}; B_S = B_S\text{ opt}$

$$F \quad \text{typ.} \quad 2.0\text{ dB}$$

$$\text{max.} \quad 3.0\text{ dB}$$

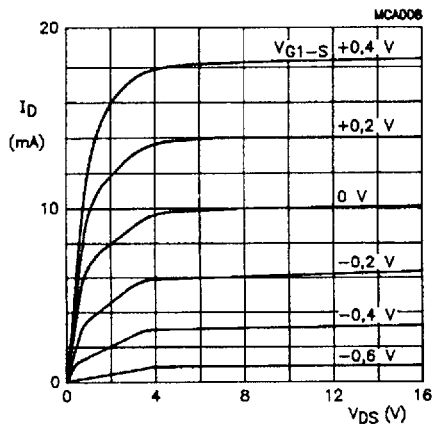


Fig.3 Output characteristics.
 $V_{G2-S} = 4 \text{ V}$; $T_{amb} = 25 \text{ }^\circ\text{C}$.

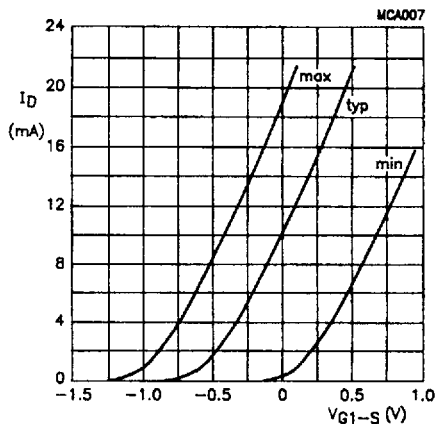


Fig.4 Transfer characteristics.
 $V_{DS} = 10 \text{ V}$; $V_{G2-S} = 4 \text{ V}$;
 $T_{amb} = 25 \text{ }^\circ\text{C}$.

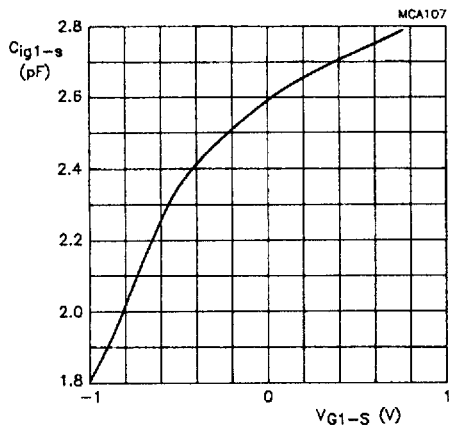


Fig.5 Gate 1 input capacitance as a function of gate 1 source voltage;
 $f = 1 \text{ MHz}$; $V_{DS} = 10 \text{ V}$; $V_{G2-S} = 4 \text{ V}$;
 $T_{amb} = 25 \text{ }^\circ\text{C}$.

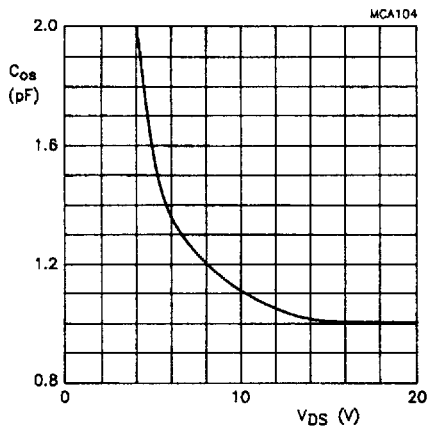


Fig.6 Output capacitance as a function of drain voltage; $f = 1 \text{ MHz}$;
 $I_D = 10 \text{ mA}$; $V_{G2-S} = 4 \text{ V}$;
 $T_{amb} = 25 \text{ }^\circ\text{C}$.

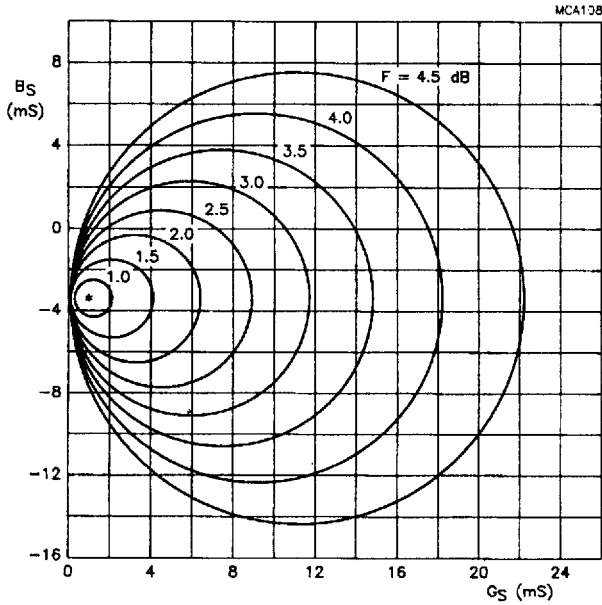


Fig.7 Circles of constant noise figures; $f = 200 \text{ MHz}$;
 $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$; $V_{\text{DS}} = 10 \text{ V}$; $V_{\text{G2-S}} = 4 \text{ V}$; $I_{\text{D}} = 10 \text{ mA}$.

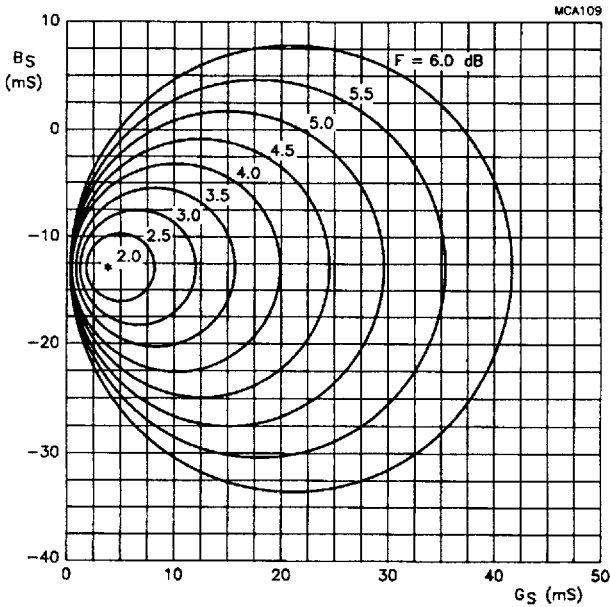


Fig.8 Circles of constant noise figures; $f = 800 \text{ MHz}$;
 $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$; $V_{\text{DS}} = 10 \text{ V}$; $V_{\text{G2-S}} = 4 \text{ V}$; $I_{\text{D}} = 10 \text{ mA}$.

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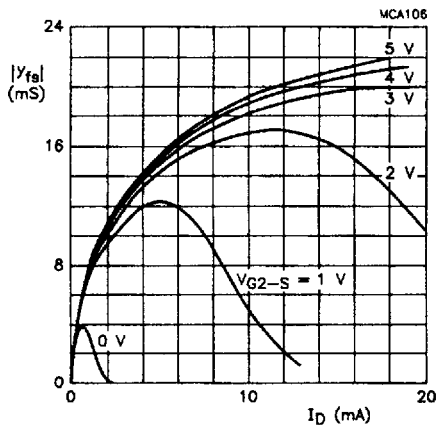


Fig.9 Forward transfer admittance as a function of drain current; $f = 1$ kHz; $V_{DS} = 10$ V; $T_{amb} = 25$ °C.

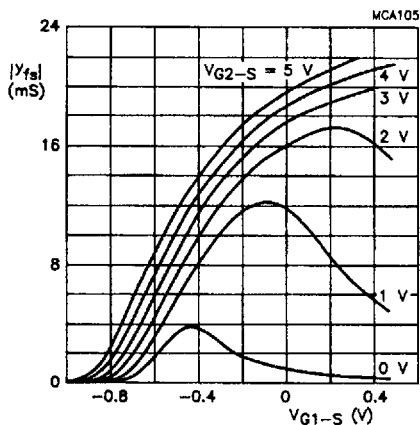


Fig.10 Forward transfer admittance as a function of gate 1 source voltage; $f = 1$ kHz; $V_{DS} = 10$ V; $T_{amb} = 25$ °C.